

**PMP10018\_RevB**

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C1	1	DNP		TBD	TBD	
C2	1	DNP	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	1206	Used in BOM report	Used in BOM report
C3	1	2.2uF	CAP, CERM, 2.2uF, 16V, +/-10%, X7R, 1206	1206	C1206C225K4RACTU	Kemet
C4	1	0.01uF	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H103KA01D	MuRata
C5	1	47uF	CAP, CERM, 47uF, 6.3V, +/-10%, X7R, 1210	1210	GRM32ER70J476KE20L	MuRata
C6	1	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603	06035C104KAT2A	AVX
C7	1	4700pF	CAP, CERM, 4700pF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H472KA01D	MuRata
C8	1	DNP	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0603	Used in BOM report	Used in BOM report
D1	1	20V	Diode, Schottky, 20V, 1A, SMA	SMA	MBRA120	ON Semiconductor
J1, J2	2		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm	ED555/2DS	On-Shore Technology
L1	1	22uH	Inductor, Shielded Drum Core, Ferrite, 22uH, 0.97A, 0.18 ohm, SMD	MOS6020	MOS6020-223MLB	Coilcraft
R1	1	69.8k	RES, 69.8k ohm, 1%, 0.1W, 0603	0603	CRCW060369K8FKEA	Vishay-Dale
R2	1	15.4k	RES, 15.4k ohm, 1%, 0.1W, 0603	0603	CRCW060315K4FKEA	Vishay-Dale
R3	1	118k	RES, 118k ohm, 1%, 0.1W, 0603	0603	CRCW0603118KFKEA	Vishay-Dale
R4	1	100k	RES, 100k ohm, 1%, 0.1W, 0603	0603	CRCW0603100KFKEA	Vishay-Dale
R5	1	49.9	RES, 49.9 ohm, 1%, 0.1W, 0603	0603	CRCW060349R9FKEA	Vishay-Dale
R6	1	49.9k	RES, 49.9k ohm, 1%, 0.1W, 0603	0603	CRCW060349K9FKEA	Vishay-Dale
R7	1	15.8k	RES, 15.8k ohm, 1%, 0.1W, 0603	0603	CRCW060315K8FKEA	Vishay-Dale
TP1, TP3, TP4, TP5, TP6, TP7, TP8, TP9	8	Red	Test Point, Miniature, Red, TH	Red Miniature Testpoint	5000	Keystone
TP2, TP10	2	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
U1	1	TPS54040DGQ (alternative:TPS57040-Q1)	IC, Swift DC-DC Converter With Eco-Mode, 0.5A, 42V	MSOP-10	TPS54040DGQ (alternative:TPS57040-Q1)	TI

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